

IN THE ABSTRACT:

Please amend the abstract as follows:

~~The present invention provides a~~ A surface-mount SAW device configured to prevent sealing resin layer coated all over the top surface of a piezoelectric substrate from becoming charged even if the piezoelectric substrate forming the SAW device is made of a pyroelectric material. The SAW device is composed of[[1]] a mounting substrate [[2]]; a SAW chip [[15]] provided with a piezoelectric substrate [[18]], an IDT electrode [[17]] formed on one surface of said piezoelectric substrate, and connection pads [[16]] connected via conductor bumps [[10]] to conductor traces [[5]]; a flip chip mounted to the mounting substrate; and a sealing resin layer [[21]] coated all over the outer surface of the SAW chip flip-chip mounted on the mounting substrate and extended down to the top surface of the mounting substrate to define an airtight space [[S]] between the IDT electrode and the mounting substrate; and wherein ~~the crystal structure of the piezoelectric substrate belongs to any one of point groups C_4 , C_2 , C_6 , C_{2V} , C_4 , C_{4V} , C_3 , C_{3V} , C_6 and C_{6V} in terms of Schoenflies symbols; characterized in that the~~ electrical conductivity of the piezoelectric substrate is increased to suppress charging of the sealing resin layer.